

Title (en)  
FABRICATING AN MTJ WITH LOW AREAL RESISTANCE

Title (de)  
FABIKATION EINES MTJ MIT NIEDRIGEM FLÄCHENWIDERSTAND

Title (fr)  
PRODUCTION D'UNE JONCTION MAGNETIQUE A EFFET TUNNEL A FAIBLE RESISTANCE SURFACIQUE

Publication  
**EP 1038325 A1 20000927 (EN)**

Application  
**EP 99934121 A 19990715**

Priority  
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• US 11932698 A 19980720

Abstract (en)  
[origin: WO0004592A1] A method of fabricating a magnetoresistive tunnel junction including forming a thin, continuous layer of aluminum alloy (15) on the surface of a first magnetic layer (11), the continuous layer of aluminum alloy including greater than 90 % aluminum and traces of materials having atoms that are different from the atoms of the aluminum to produce grains which are smaller than grains of pure aluminum. The continuous layer (16) of aluminum alloy is oxidized, nitridized, or both to produce a continuous layer of non-conductive material and a second magnetic layer (18) is formed on the layer of non-conductive material.

IPC 1-7  
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IPC 8 full level  
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**B82Y 25/00** (2013.01 - EP US); **G01R 33/093** (2013.01 - EP US); **G01R 33/098** (2013.01 - EP US); **G11C 11/161** (2013.01 - EP US); **H01F 10/3254** (2013.01 - EP US); **H10N 50/00** (2023.02 - KR); **H10N 50/01** (2023.02 - EP US); **H10N 50/10** (2023.02 - EP US)

Citation (search report)  
See references of WO 0004592A1

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